Global 2.5D and 3D TSV Market 2025 by Company, Regions, Type and Application, Forecast to 2031

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Abstracts

According to our (Global Info Research) latest study, the global 2.5D and 3D TSV market size was valued at US$ 11130 million in 2024 and is forecast to a readjusted size of USD 24780 million by 2031 with a CAGR of 12.6% during review period.

2.5D and 3D packaging are inseparable from TSV technology, and the integration of 2.D and 3D must be achieved through TSV.

Specifically, 2.5D packaging technology uses a silicon interposer to lay out multiple chips or dies side by side with components such as high-bandwidth memory, and uses micro-bumps or micro-bumps on the interposer as efficient interconnection bridges, significantly enhancing Improves data transfer rate and overall system performance. The core of 3D packaging technology is to use TSV technology to realize vertical stacking and interconnection of chips. This innovation not only greatly reduces the chip size, improves the integration density and performance, but also effectively reduces power consumption and heat dissipation requirements, further enhancing The reliability and stability of the system.

The downstream of 2.D and 3D TSV packaging is mainly used in HPC, AR/VR, games, network switches and routers, MEMS, CIS and LED, etc. As early as 2007, Intel took the lead in introducing 2.5D packaging technology, the core concept of which is to use silicon interposers to achieve high-density interconnection between chips. Since then, TSMC, Samsung and other companies have actively participated in research and development, and jointly promoted the increasing maturity of 2.5D packaging technology. At the same time, 3D packaging technology began to emerge in the early 21st century. The key lies in the use of TSV technology to achieve vertical stacking connection of chips. In the 2010s, with the significant progress of TSV technology, 3D

packaging technology was first applied in the memory field, and gradually penetrated into multiple fields such as logic chips and RF chips. In recent years, 2.5D and 3D TSV packaging technologies have gradually penetrated into the fields of artificial intelligence and 5G communications. In the future, these two fields will become the main driving force for the growth of this market.

The manufacturing process of 2.5D and 3D TSV packaging includes wafer manufacturing, which involves multiple process steps such as lithography, etching, ion implantation, and thin film deposition. Each step requires special equipment, such as TSV etching equipment and TSV deposition equipment. In this field, the core companies mainly include Applied Materials, Lam Research, TEL, Samco Inc, ULVAC, and North China Huachuang. From the perspective of market competition, Japanese and American companies have a greater competitive advantage in the TSV packaging equipment market.

In the 2.5D and 3D TSV packaging market, there are mainly IDM and packaging and testing companies. Among them, the leading representative company TSMC has rich production experience in the 2.5D and 3D packaging market. Its 2.5D/3D packaging technologies are CoWoS and SoIC respectively.

In terms of regional markets, mainland China accounts for about 23% of the 2.5D and 3D TSV packaging market. As the leader in the consumer electronics market, mainland China has shown a huge demand for high-performance and low-power semiconductor chips. This situation has greatly promoted the market application potential of 2.5D and 3D packaging technologies. At the same time, the Chinese government actively supports the semiconductor industry and implements a series of incentive policies to stimulate the R&D vitality of enterprises and promote technological innovation. In the field of semiconductor manufacturing, China has made great progress. The continuous enhancement of wafer manufacturing capabilities has provided strong support for the vigorous development of the packaging industry. It is expected that by 2030, the Chinese mainland market share will reach 25%.

This report is a detailed and comprehensive analysis for global 2.5D and 3D TSV market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global 2.5D and 3D TSV market size and forecasts, in consumption value ($ Million), 2020-2031

Global 2.5D and 3D TSV market size and forecasts by region and country, in consumption value ($ Million), 2020-2031

Global 2.5D and 3D TSV market size and forecasts, by Type and by Application, in consumption value ($ Million), 2020-2031

Global 2.5D and 3D TSV market shares of main players, in revenue ($ Million), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for 2.5D and 3D TSV
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global 2.5D and 3D TSV market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include TSMC, Samsung, Intel, ASE Group, Amkor Technology, SPIL, Powertech Technology, JCET Group, GlobalFoundries Inc, Tezzaron Semiconductor, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

2.5D and 3D TSV market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

- 2.5D TSV
- 3D TSV

Market segment by Application

- Memory
- CIS
- SoC
- MEMS
- Others

Market segment by players, this report covers

- TSMC
- Samsung
- Intel
- ASE Group
- Amkor Technology
- SPIL
- Powertech Technology
- JCET Group
- GlobalFoundries Inc

Tezzaron Semiconductor

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)
Europe (Germany, France, UK, Russia, Italy and Rest of Europe)
Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)
South America (Brazil, Rest of South America)
Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe 2.5D and 3D TSV product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of 2.5D and 3D TSV, with revenue, gross margin, and global market share of 2.5D and 3D TSV from 2020 to 2025.

Chapter 3, the 2.5D and 3D TSV competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2020 to 2031

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2020 to 2025.and 2.5D and 3D TSV market forecast, by regions, by Type and by Application, with consumption value, from 2026 to 2031.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of 2.5D and 3D TSV.

Chapter 13, to describe 2.5D and 3D TSV research findings and conclusion.

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